



Material Content Data Sheet



Sales Product Name				BSC040N10NS5		Issued		30. July 2019	
MA#				MA003954976					
Package				PG-TDSON-8-50		Weight*		107.35 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.517	1.41	1.41	14133	14133	
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		127		
	non noble metal	zinc	7440-66-6	0.055	0.05		508		
	non noble metal	iron	7439-89-6	1.090	1.02		10156		
wire	non noble metal	copper	7440-50-8	44.271	41.23	42.31	412387	423178	
	noble metal	gold	7440-57-5	0.042	0.04	0.04	388	388	
	encapsulation	organic material	carbon black	1333-86-4	0.083	0.08		777	
plastics	plastics	epoxy resin	-	3.835	3.57		35727		
	inorganic material	silicondioxide	60676-86-0	37.771	35.18	38.83	351836	388340	
leadfinish	non noble metal	tin	7440-31-5	1.264	1.18	1.18	11772	11772	
plating	noble metal	silver	7440-22-4	0.029	0.03	0.03	270	270	
solder	noble metal	silver	7440-22-4	0.052	0.05		480		
	non noble metal	tin	7440-31-5	0.103	0.10		960		
	non noble metal	lead	7439-92-1	1.907	1.78	1.93	17768	19208	
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005	0.00		43		
	non noble metal	zinc	7440-66-6	0.018	0.02		171		
	non noble metal	iron	7439-89-6	0.368	0.34		3425		
	non noble metal	copper	7440-50-8	14.930	13.91	14.27	139072	142711	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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